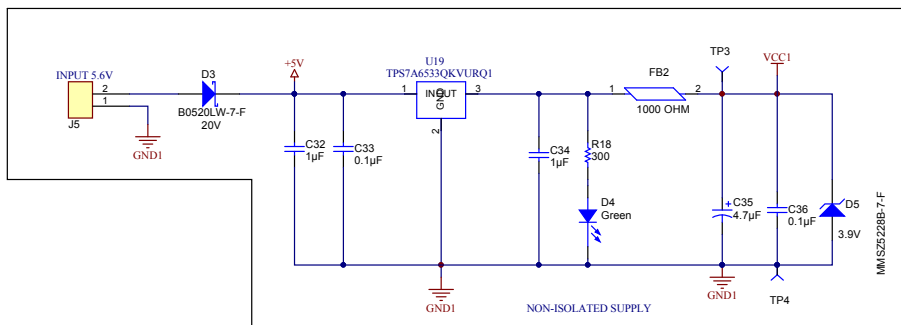
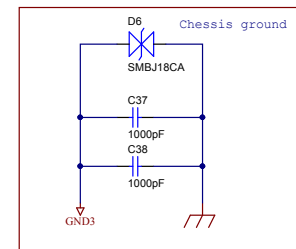
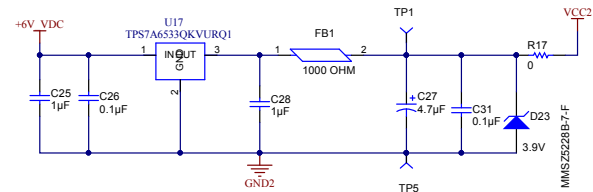
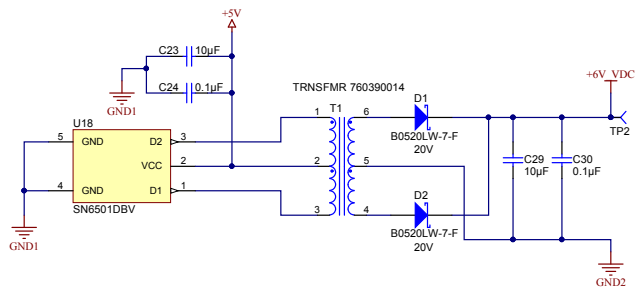


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Number: TIDA-00557	Rev: A0	Sheet Title: Assembly Variant: 001	Sheet: 4 of 5
SVN Rev. Not in version control	Drawn By: SUNIL DWIVEDI	File: Page4 Power Supply_SchDoc	Size: B
Engineer: SUNIL DWIVEDI	Designed for: Public Release	Mod. Date: 5/29/2015	Project Title: Full Modem Control with RS-232
		Contact: http://www.ti.com/support	http://www.ti.com



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H1 NY PMS 440 0025 PH H2 NY PMS 440 0025 PH H3 NY PMS 440 0025 PH H4 NY PMS 440 0025 PH H9 NY PMS 440 0025 PH

H5 1902C H6 1902C H7 1902C H8 1902C H10 1902C

~~HID1~~ ~~HID2~~ ~~HID3~~

PCB Number: TIDA-00557
PCB Rev: E2

PCB
LOGO
Texas Instruments

You should delete the nylon screws/standoffs and/or the bump-ons as needed for your design (or substitute other parts from Hardware.IntLib). Bump-ons are cheaper, but provide less clearance.

Deleting anything else from this page may result in your EVM submission being rejected (until you add them back).

Update the Label Text in the Label Table as needed for each Assembly Variant.

You can delete this note too.

Label Table	
Variant	Label Text
001	ChangeMe!
002	ChangeMe!

LBL1
PCB Label
Size: 0.65" x 0.20"


ZZ1
Label Assembly Note
This Assembly Note is for PCB labels only

ZZ2
Assembly Note
These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ3
Assembly Note
These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ4
Assembly Note
These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

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Number: TIDA-00557	Rev: A0	Designed for: Public Release	Mod. Date: 5/29/2015
SVN Rev. Not in version control	Assembly Variant: 001	Project Title: Full Modem Control with RS-232	Sheet Title:
Drawn By:	File: Page5 Hardware ANSI-B.SchDoc	Sheet: 5 of 5	Size: B
Engineer: SUNIL DWIVEDI	Contact: http://www.ti.com/support	 http://www.ti.com <small>© Texas Instruments 2015</small>	

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